



Middle production line for SMD assembling

Line capacity: **57 000 CPH**

A ready solution for contract manufacturing or companies with own manufacturing. Complex of equipment included in one functional line enables solution of main tasks for PCB assembly of various complexity.

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The line equipment is capable of assembling PCBs up to 510 x 460 mm with speed up to 57,000 CPH.

Quality control of product assembled in the line occurs in 2 stages: after solder paste printing and on the last assembly stage, after reflowing in the oven.

Solder paste application in printer is controlled by built-in 3D control system.

An optical inspection system programmed for testing of ready product is located after the reflow oven as well.

Additional software enables preparing PCB assembly program in offline mode.

It is possible to changeover the line for a new product in a few minutes using intellectual feeders and trolley feeder bases.

Line specification	Vendor	Model
PCB loader to line	SJ Inno tech	SLD-120X
Solder paste printer	SJ Inno tech	HP-520SPI
Sorting conveyer	SJ Inno tech	KNC-600X
SMD pick-and place system	Mirae	Mx-400
SMD pick-and place system	Mirae	Mx-200P
Visual check work table	SJ Inno tech	SWT-900X
Solder paste reflow oven	TSM	A70-j102s
Optical inspection system	Mirtec	MV-7Xi
PCBs NG buffer	SJ Inno tech	SRB-100X
PCB unloader from line	SJ Inno tech	SUD-120X



Options list:

For SMD pick-and-place system

- Trolley with feeder bases for quick changeover to a new product
- Offline programming software for faster creation of programs
- System of barcode reading from component reels for convenient work of electronic warehouse
- Classic reel tape feeders (C-Feeder) for tape 8 – 88 mm
- High-speed reel tape feeders (eX-Feeder) for tape 8 – 88 mm
- Stick feeder for 6 sticks
- Manual tray feeder for IC in JEDEC pallets
- Automatic tray feeder for 20 JEDEC pallets
- Software for remote monitoring and statistics collection from the line in online mode

For solder paste printer

- Pneumatic support pins
- Automatic adding of solder paste
- Microclimate support system

For solder paste reflow oven

- Thermal profiler to control temperature at PCB surface
- Nitrogen connection option

Line specification:

- PCB size: from 50 x 50 mm up to 510 x 460 mm
- Speed according to IPC-9850: 57,000 CPH for chip components and 1,200 CPH for IC
- Components: from 01005 up to 50 x 50 mm (or 90 x 30 mm for oblong components), max. height of component 18 mm
- Quantity of 8 mm feeders: 200 ea.
- Component placing precision: $\pm 25 \mu\text{m}$ (at 3σ)
- Solder paste application control: built-in 3D system
- Optical inspection system with side view cameras
- Measuring of IC leads height
- Laser control of IC leads soldering
- Oven: 10 heating zones, 2 cooling zone

